

To : Dear Valued Customers

Product/Process Change Notice

We hereby submit PCN for your review and approval.

Application or type : Wire bond process and Lead frame change.

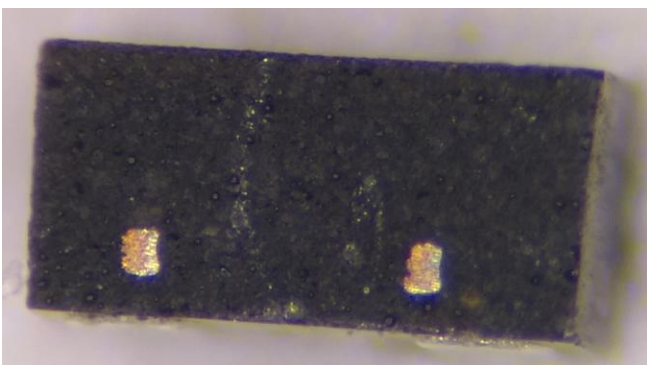
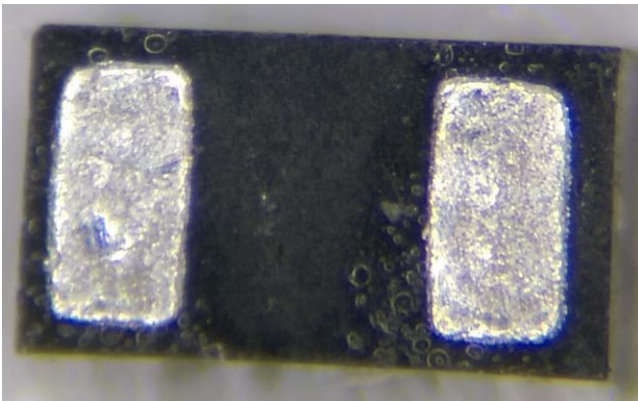
Detail of the change :

The wire bond process of ACPDQC3V3T-HF & CPDQC3V3T-HF Al will change from Al wire to Gold wire process.

The Lead frame change of ACPDQC3V3T-HF & CPDQC3V3T-HF.

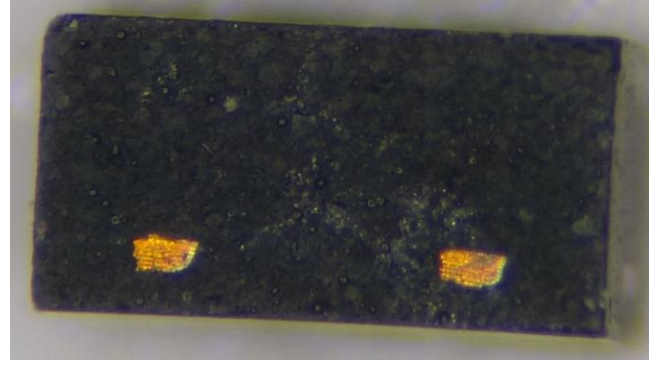
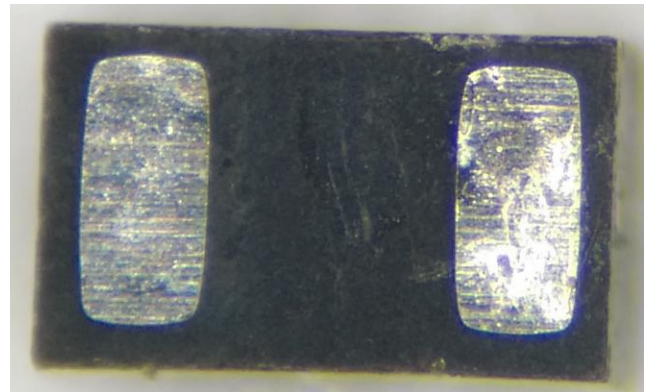
Current :

Al wire process & Old Lead frame



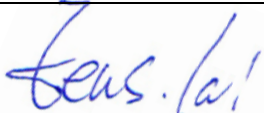
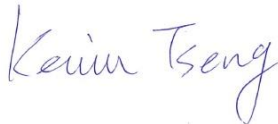
After the change :

Gold wire process & New Lead frame



Reason for the change :

1. To improve the stability of loop height of Al wire process, we will use Gold wire process to produce ACPDQC3V3T-HF & CPDQC3V3T-HF.
2. To improve the yield and reliability of finish goods.

Evaluation items : Reliability Test Report. 201604A02-034-ACPDQC3V3T-HF	
Implemented from : Effective Date : Jan. 1th, 2016	
R&D Dept. Signature : 	QA Dept. Signature : 

Answer To PCN

Please complete the form below duly signed and fax back to Comchip Technology Co.

Please select your answer 1. <input type="checkbox"/> Approved this PCN 2. <input type="checkbox"/> Approved this PCN with conditions 3. <input type="checkbox"/> Disapproved this PCN	Date
	Responsibility By
Please specify the condition or explain the reason if you select 2 or 3. <input type="checkbox"/> We disagree with this proposed change and the schedule. Reason: <input type="checkbox"/> We need samples.	

Unless a Comchip Technology Co., Ltd. Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.